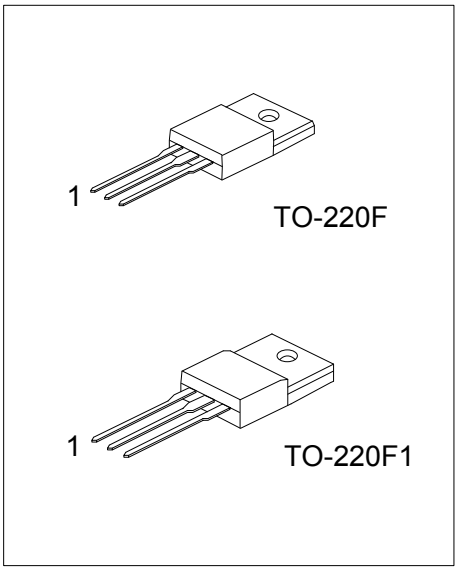
4N70

Power MOSFET

4 Amps, 700 Volts
N-CHANNEL POWER MOSFET



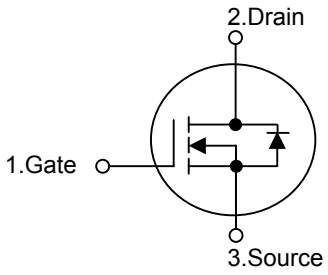
■ DESCRIPTION

The UTC **4N70** is a high voltage MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and high rugged avalanche. This high speed switching power MOSFET is usually used in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

■ FEATURES

* $R_{DS(ON)}$ = 2.8Ω @V_{GS} = 10 V
* Ultra Low Gate Charge (Typical 15 nC)
* Low Reverse Transfer Capacitance (C_{RSS} = Typical 8.0 pF)
* Fast Switching Capability
* Avalanche Energy Specified
* Improved dv/dt Capability, High Ruggedness

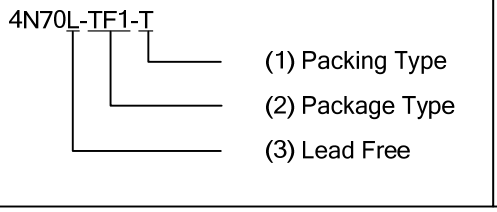
■ SYMBOL



■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
4N70L-TF1-T	4N70G-TF1-T	TO-220F1	G	D	S	Tube
4N70L-TF3-T	4N70G-TF3-T	TO-220F	G	D	S	Tube

Note: Pin Assignment: G: Gate D: Drain S: Source



(1) T: Tube

(2) TF1: TO-220F1, TF3: TO-220F

(3) G: Halogen Free, L: Lead Free

■ ABSOLUTE MAXIMUM RATINGS (Ta = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	700	V
Gate-Source Voltage		V_{GSS}	±30	V
Avalanche Current (Note 2)		I_{AR}	4.4	A
Drain Current	Continuous	I_D	4.0	A
	Pulsed (Note 2)	I_{DM}	16	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	260	mJ
	Repetitive (Note 2)	E_{AR}	10.6	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.5	V/ns
Power Dissipation		P_D	36	W
Junction Temperature		T_J	+150	°C
Operating Temperature		T_{OPR}	-55 ~ +150	°C
Storage Temperature		T_{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating : Pulse width limited by maximum junction temperature
3. L = 30mH, I_{AS} = 4A, V_{DD} = 50V, R_G = 25 Ω, Starting T_J = 25°C
4. I_{SD}≤ 4.4A, di/dt ≤200A/μs, V_{DD}≤ BV_{DSS}, Starting T_J = 25°C

■ THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ_{JA}	62.5	°C/W
Junction to Case	θ_{Jc}	3.47	°C/W

■ ELECTRICAL CHARACTERISTICS (Ta =25°C, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV_{DSS}	V_{GS} = 0 V, I_D = 250 μA	700			V
Drain-Source Leakage Current		I_{DSS}	V_{DS} = 700 V, V_{GS} = 0 V			10	μA
Gate-Source Leakage Current	Forward	I_{GSS}	V_{GS} = 30 V, V_{DS} = 0 V			100	nA
	Reverse		V_{GS} = -30 V, V_{DS} = 0 V			-100	
Breakdown Voltage Temperature Coefficient		$\frac{\Delta BV_{DSS}}{T_J}$	I_D = 250 μA, Referenced to 25°C		0.6		V/°C
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	V_{DS} = V_{GS}, I_D = 250 μA	2.0		4.0	V
Static Drain-Source On-State Resistance		$R_{DS(ON)}$	V_{GS} = 10 V, I_D = 2.2 A			2.8	Ω
DYNAMIC CHARACTERISTICS							
Input Capacitance		C_{ISS}	V_{DS} = 25 V, V_{GS} = 0 V, f = 1MHz		520	670	pF
Output Capacitance		C_{OSS}			70	90	pF
Reverse Transfer Capacitance		C_{RSS}			8	11	pF
SWITCHING CHARACTERISTICS							
Turn-On Delay Time		$t_{D(ON)}$	V_{DD} = 350V, I_D = 4.0A, R_G = 25Ω (Note 1, 2)		13	35	ns
Turn-On Rise Time		t_R			45	100	ns
Turn-Off Delay Time		$t_{D(OFF)}$			25	60	ns
Turn-Off Fall Time		t_F			35	80	ns
Total Gate Charge		Q_G	V_{DS}= 560V, I_D= 4.0A, V_{GS}= 10 V (Note 1, 2)		15	20	nC
Gate-Source Charge		Q_{GS}			3.4		nC
Gate-Drain Charge		Q_{GD}			7.1		nC

■ ELECTRICAL CHARACTERISTICS(Cont.)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Drain-Source Diode Forward Voltage	V_{SD}	V_{GS} = 0 V, I_S = 4.4 A			1.4	V
Maximum Continuous Drain-Source Diode Forward Current	I_S				4.4	A
Maximum Pulsed Drain-Source Diode Forward Current	I_{SM}				17.6	A
Reverse Recovery Time	t_{RR}	V_{GS} = 0 V, I_S = 4.4 A, dI/dt = 100 A/μs (Note 1)		250		ns
Reverse Recovery Charge	Q_{RR}			1.5		μC

Notes: 1. Pulse Test: Pulse width≤300μs, Duty cycle≤2%
2. Essentially independent of operating temperature

■ TEST CIRCUITS AND WAVEFORMS

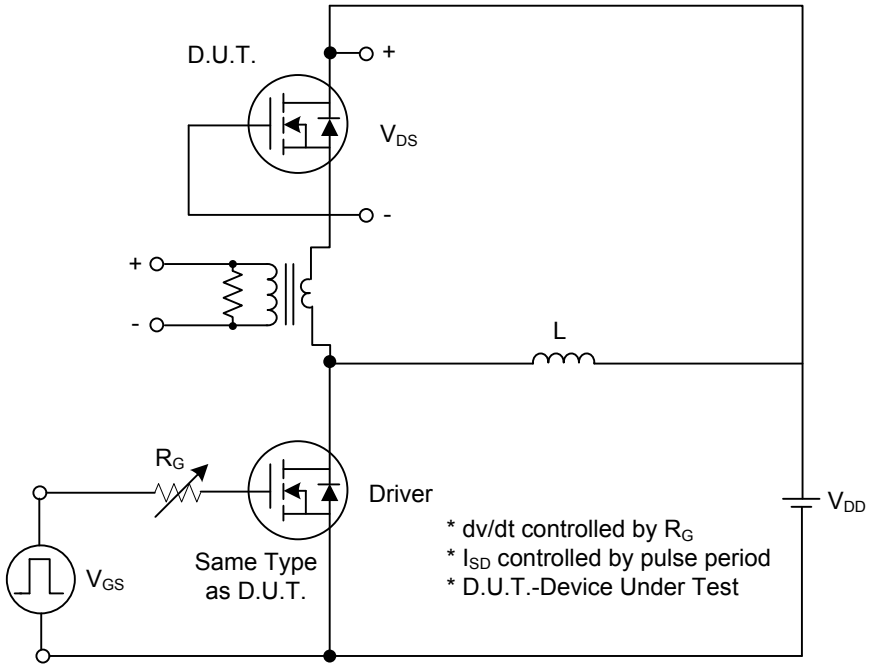


Fig. 1A Peak Diode Recovery dv/dt Test Circuit

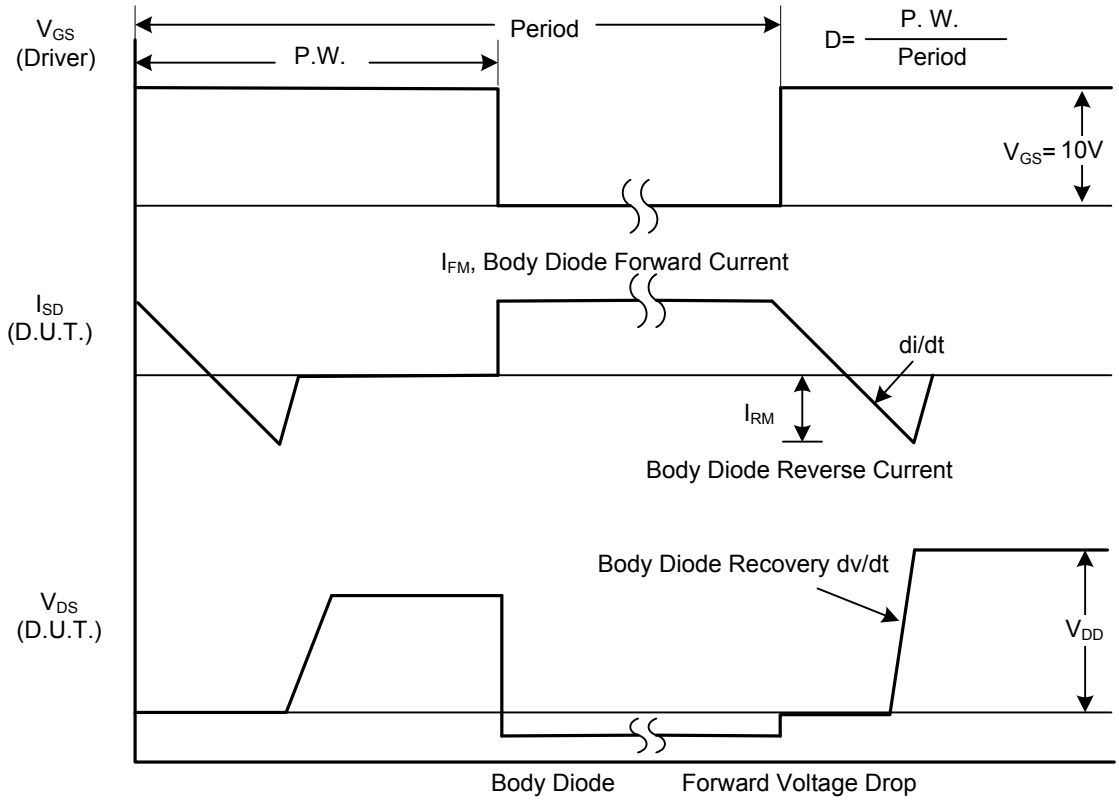


Fig. 1B Peak Diode Recovery dv/dt Waveforms

■ TEST CIRCUITS AND WAVEFORMS (Cont.)

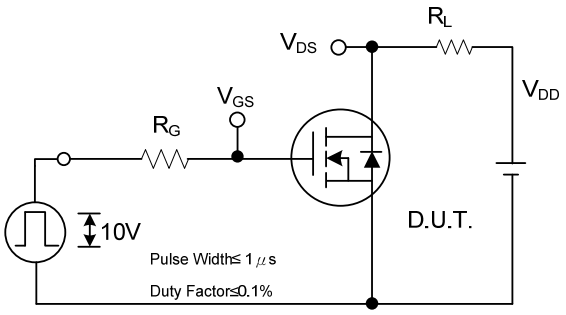


Fig. 2A Switching Test Circuit

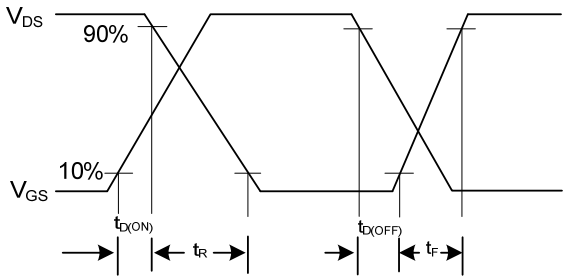


Fig. 2B Switching Waveforms

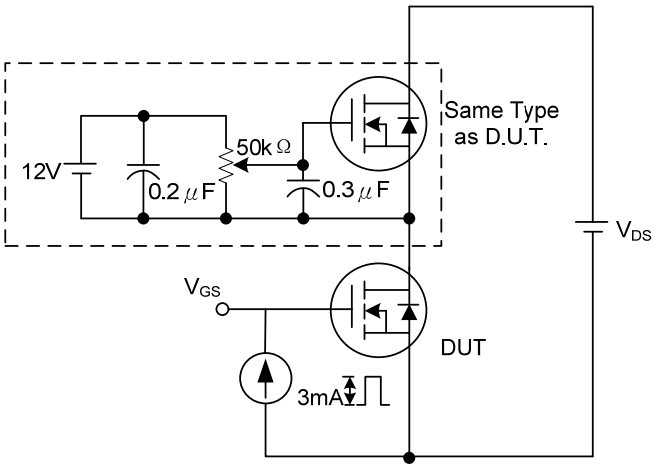


Fig. 3A Gate Charge Test Circuit

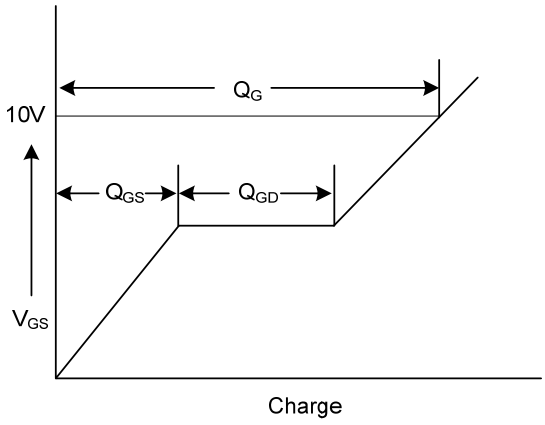


Fig. 3B Gate Charge Waveform

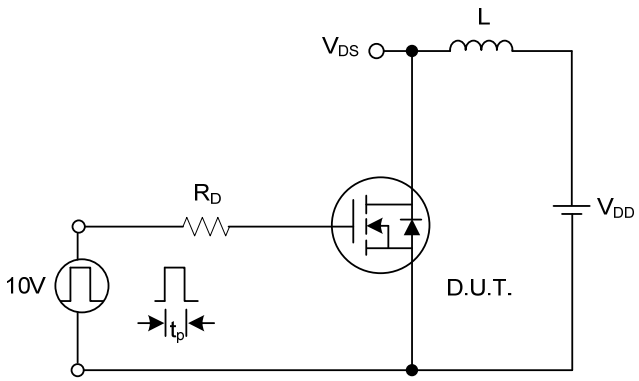


Fig. 4A Unclamped Inductive Switching Test Circuit

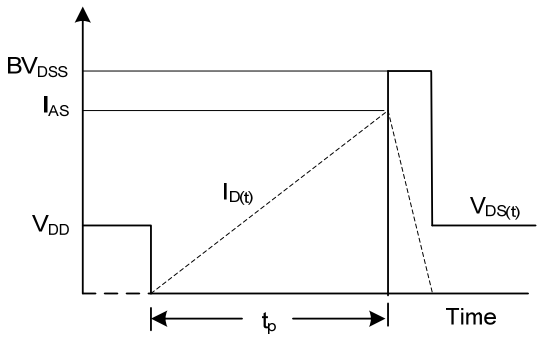
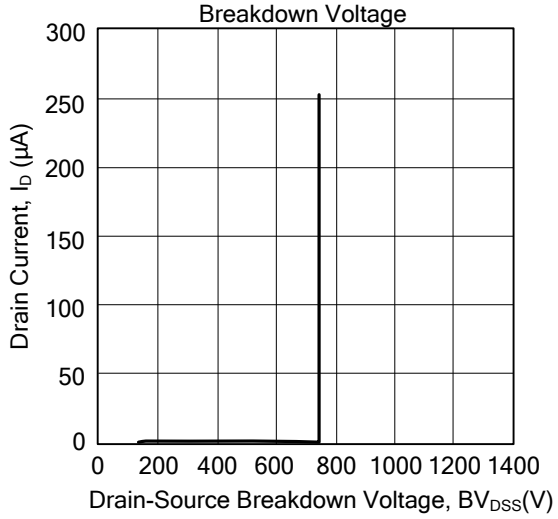


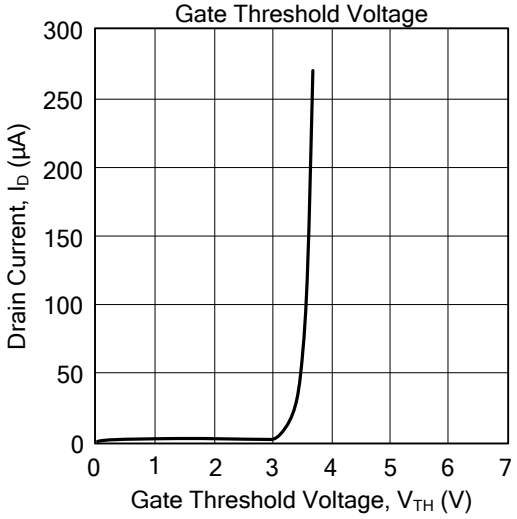
Fig. 4B Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS

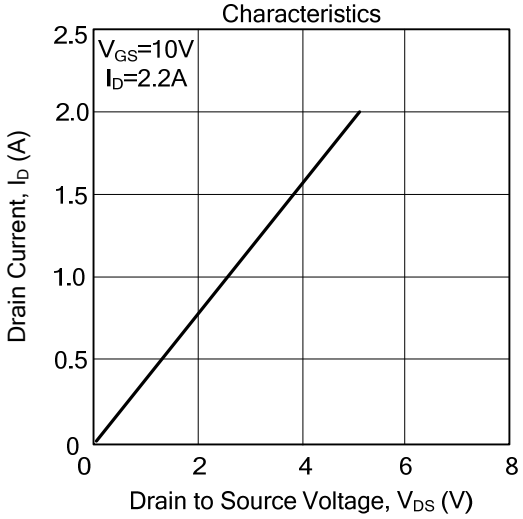
Drain Current vs. Drain-Source Breakdown Voltage



Drain Current vs. Gate Threshold Voltage



Drain-Source On-State Resistance Characteristics



Drain Current vs. Source to Drain Voltage